

MBRS4201T3

200V, 4A Schottky Fast Soft-Recovery Power Rectifier

SMC Power Surface Mount Package

Features

- Lower Forward Voltage than any Ultrafast Rectifier:
 $V_F < 0.61\text{ V}$ at 150°C
- Fast Switching Speed: Reverse Recovery Time (t_{RR}) $< 35\text{ ns}$
- Soft Recovery Characteristics: Softness Factor (t_b/t_a) ≥ 1
- Highly Stable Over Temperature
- This is a Pb-Free Device

Benefits

- Significantly Reduced EMI
- Eliminates the Need of Snubber Circuits
- Low Switching and Heat Losses
- Improved Thermal Management

Applications

- Engine and Convenience Control Systems
- Motor Controls
- Battery Chargers and Switching Power Supplies

Mechanical Characteristics

- Small Compact Surface Mount Package with J-Bend Leads
- Rectangular Package for Automated Handling
- Weight: 217 mg (Approximately)
- Finish: All External Surfaces Corrosion Resistant and Terminal Leads are Readily Solderable
- Lead and Mounting Surface Temperature for Soldering Purposes: 260°C Maximum for 10 Seconds
- Polarity: Notch in Plastic Body Indicates Cathode Lead

MAXIMUM RATINGS

Characteristic	Symbol	Value	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V_{RRM} V_{RWM} V_R	200	V
Average Rectified Forward Current (Rated V_R , $T_L = 70^\circ\text{C}$)	$I_{F(AV)}$	4	A
Nonrepetitive Peak Surge Current (Surge Applied at Rated Load Conditions Halfwave, Single Phase, 60 Hz)	I_{FSM}	100	A
Operating Junction Temperature	T_J	-55 to +150	$^\circ\text{C}$

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.



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SCHOTTKY RECTIFIER 4 AMPS, 200 VOLTS



SMC
CASE 403
PLASTIC

MARKING DIAGRAM



B421 = Specific Device Code
A = Assembly Location
Y = Year
WW = Work Week
▪ = Pb-Free Package
(Note: Microdot may be in either location)

ORDERING INFORMATION

Device	Package	Shipping†
MBRS4201T3G	SMC (Pb-Free)	2500 / Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification Brochure, BRD8011/D.

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THERMAL CHARACTERISTICS

Characteristic	Symbol	Value	Unit
Thermal Resistance, Junction-to-Lead	$R_{\theta JL}$	11	$^{\circ}\text{C}/\text{W}$

ELECTRICAL CHARACTERISTICS

Characteristic	Symbol	Value	Unit
Maximum Instantaneous Forward Voltage ($I_F = 4\text{ A}$, $T_J = 25^{\circ}\text{C}$) ($I_F = 4\text{ A}$, $T_J = 150^{\circ}\text{C}$)	V_F	0.86 0.61	V
Maximum Instantaneous Reverse Current (Rated V_R) (Rated DC Voltage, $T_J = 25^{\circ}\text{C}$) (Rated DC Voltage, $T_J = 150^{\circ}\text{C}$)	I_R	1.0 5.0	mA mA
Maximum Reverse Recovery Time ($I_F = 1.0\text{ A}$, $di/dt = 100\text{ A}/\mu\text{s}$, $V_R = 30\text{ V}$)	t_{rr}	35	ns

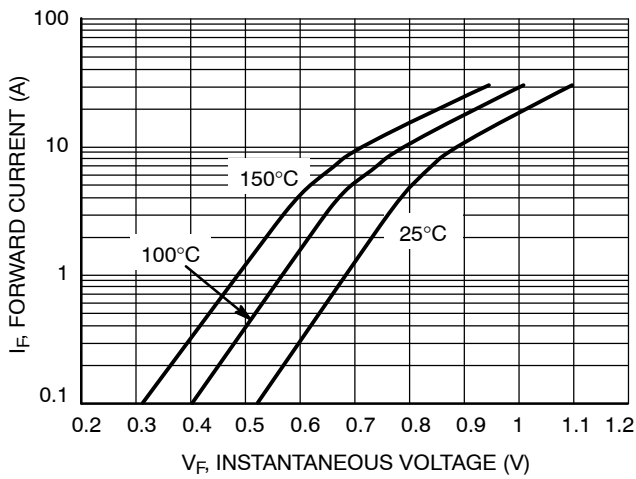


Figure 1. Typical Forward Voltage

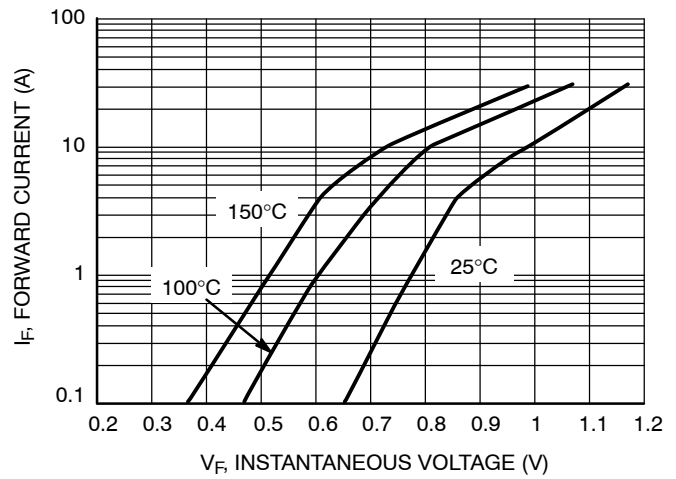


Figure 2. Maximum Forward Voltage

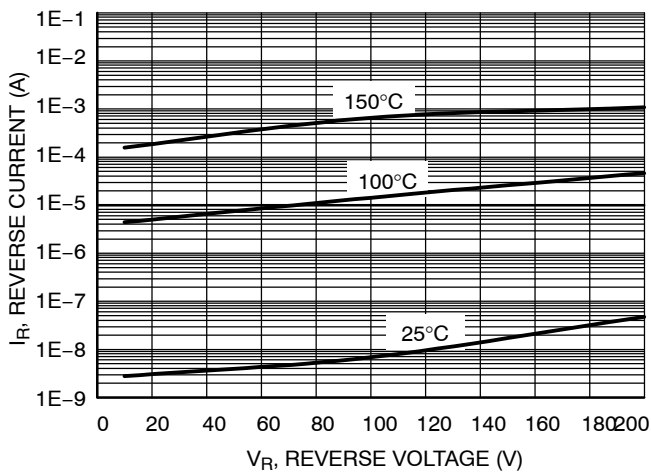


Figure 3. Typical Reverse Current

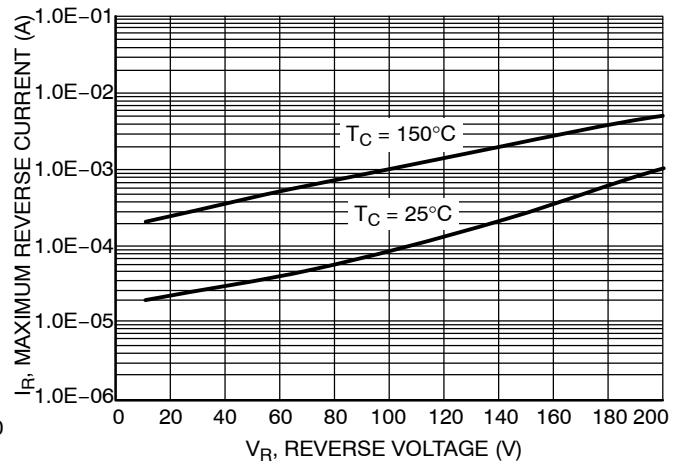


Figure 4. Maximum Reverse Current

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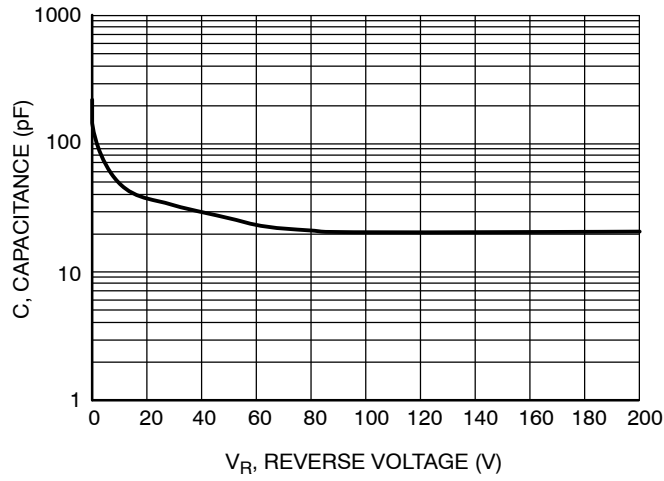


Figure 5. Typical Capacitance

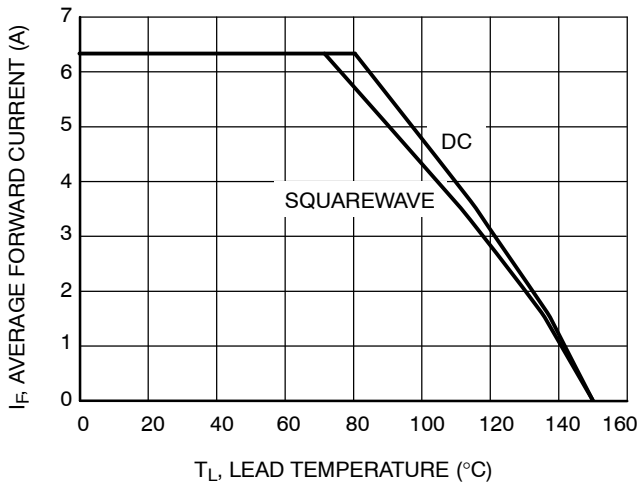


Figure 6. Derating Curve

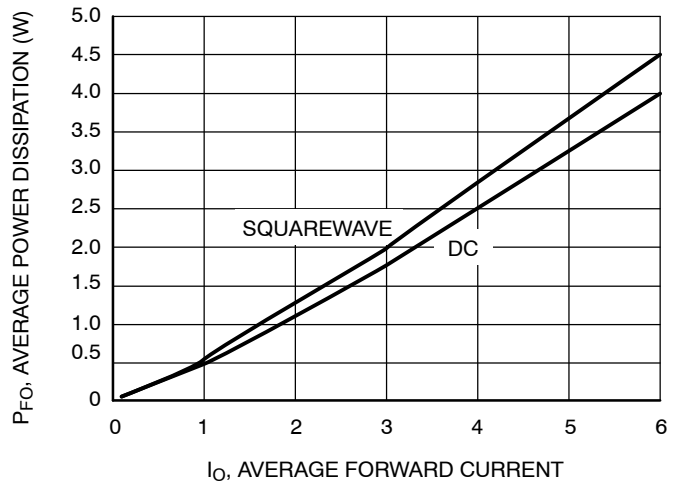
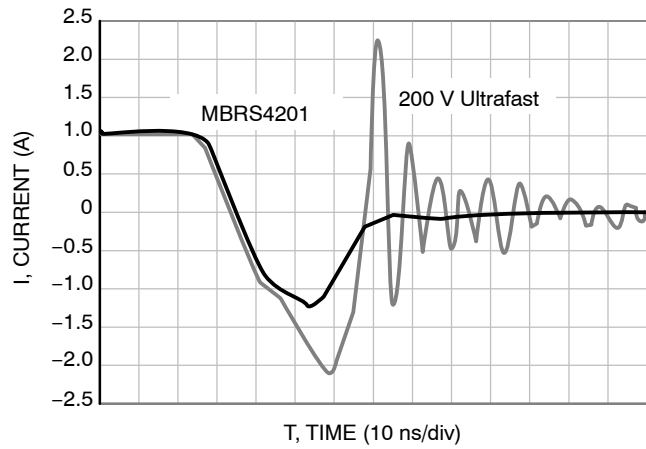


Figure 7. Power Dissipation



ON Semiconductor MBRS4201 eliminates reverse recovery oscillations present in Ultrafast devices in the market, particularly at hot temperatures.

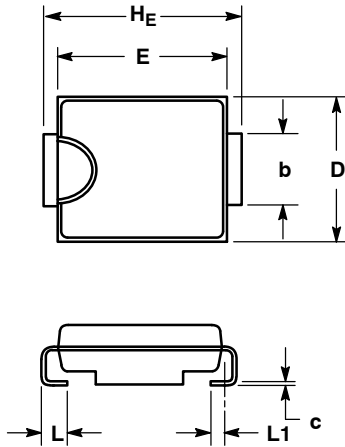
*Test Conditions:
 $I_F = 1 \text{ A}$, $d_i/d_T = 100 \text{ A}/\mu\text{s}$,
 $V_R = 30 \text{ V}$

Figure 8. Reverse Recovery Time* (t_{RR}) at 125°C

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PACKAGE DIMENSIONS

SMC
CASE 403-03
ISSUE E

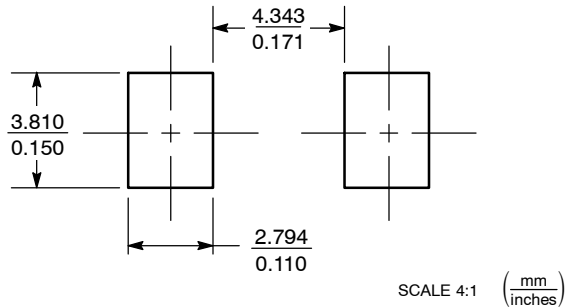


NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: INCH.
3. D DIMENSION SHALL BE MEASURED WITHIN DIMENSION P.
4. 403-01 THRU -02 OBSOLETE, NEW STANDARD 403-03.

DIM	MILLIMETERS			INCHES		
	MIN	NOM	MAX	MIN	NOM	MAX
A	1.90	2.13	2.41	0.075	0.084	0.095
A1	0.05	0.10	0.15	0.002	0.004	0.006
b	2.92	3.00	3.07	0.115	0.118	0.121
c	0.15	0.23	0.30	0.006	0.009	0.012
D	5.59	5.84	6.10	0.220	0.230	0.240
E	6.60	6.86	7.11	0.260	0.270	0.280
HE	7.75	7.94	8.13	0.305	0.313	0.320
L	0.76	1.02	1.27	0.030	0.040	0.050
L1	0.51 REF			0.020 REF		

SOLDERING FOOTPRINT*



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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